# Arteris IP FlexNoC® Interconnect Licensed by VeriSilicon for Multiple Chip Designs

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Silicon Platform as a Service company uses extensive FlexNoC expertise to create highly complex chips more quickly and efficiently

CAMPBELL, Calif. —March 13, 2018 — Arteris IP, the innovative supplier of silicon-proven commercial system-on-chip (SoC) interconnect semiconductor intellectual property (IP), today announced that VeriSilicon Holdings Co., Ltd. (VeriSilicon) has purchased multiple licenses of Arteris FlexNoC interconnect IP for use as the on-chip communications backbone of SoCs for the data center, automotive and other applications.

> *"The adoption of Arteris' unique NoC technology shortens our chip development time, lowers physical implementation difficulty and allows unparalleled optimization of SoC power, area and performance for our customers."*

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*Dr. Wayne Dai, Chairman, President and Chief Executive Officer,* ***VeriSilicon***

VeriSilicon is a Silicon Platform as a Service (SiPaaS®) company that provides comprehensive SoC solutions for a wide range of markets. The VeriSilicon team is expert in using Arteris IP to optimize SoC on-chip communications with multiple successful implementations of Arteris network-on-chip (NoC) interconnect technology in production chip designs. The SoCs implemented by VeriSilicon using Arteris interconnect IP include chips for servers, artificial intelligence and neural networks, and automotive advanced driver assistance systems (ADAS).

The multiple new FlexNoC licenses, combined with VeriSilicon's extensive experience architecting and implementing platforms, ensure that VeriSilicon's customers will have access to the lowest risk path to create highly complex chips that are optimized for power, performance and area with Arteris NoC interconnect technologies.

"Our expertise using Arteris FlexNoC IP allows us to provide our customers a unique head start in the design and development of complex systems-on-chip and IP sub-systems," said Dr. Wayne Dai, Chairman, President and Chief Executive Officer of VeriSilicon. "The adoption of Arteris' unique NoC technology shortens our chip development time, lowers physical implementation difficulty and allows unparalleled optimization of SoC power, area and performance for our customers."

"VeriSilicon's use of Arteris FlexNoC IP as the on-chip interconnect for some of the most demanding and complex chips in the world is a strong vote of confidence," said K. Charles Janac, President and CEO of Arteris IP. "As expert users of Arteris IP's technology, the VeriSilicon team is able to accelerate the development of high performance SoCs for the server, AI, automotive, and consumer electronics markets."

**About Arteris IP**

Arteris IP provides system-on-chip (SoC) interconnect IP to accelerate SoC semiconductor assembly for a wide range of applications from automobiles to mobile phones, IoT, cameras, SSD controllers, and servers for customers such as Samsung, Huawei / HiSilicon, Mobileye (Intel), Altera (Intel), and Texas Instruments. Arteris IP products include the Ncore cache coherent and FlexNoC non-coherent interconnect IP, as well as optional Resilience Package (functional safety) and PIANO automated timing closure capabilities. Customer results obtained by using the Arteris IP product line include lower power, higher performance, more efficient design reuse and faster SoC development, leading to lower development and production costs. For more information, visit www.arteris.com or find us on LinkedIn at https://www.linkedin.com/company/arteris.

**About VeriSilicon**

VeriSilicon is a Silicon Platform as a Service (SiPaaS®) company that provides industry-leading, comprehensive System-on-a-Chip (SoC) and System-in-a-Package (SiP) solutions for a wide range of end markets including mobile internet devices, datacenters, the Internet of Things (IoT), automotive, industrial, and medical electronics. Our machine learning and artificial intelligence technologies are well positioned to address the movement to "intelligent" devices. SiPaaS provides our customers a substantial head start in the semiconductor design and development process and allows the customers to focus their efforts on core competency with differentiating features. Our end-to-end semiconductor turnkey services can take a design from concept to a completed, tested, and packaged semiconductor chip in record time. The breadth and flexibility of our SiPaaS solutions make them a performance-effective and cost-efficient choice for a variety of customers. More details, please contact: press@verisilicon.com

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